

Supplier Name: Texas Instruments Inc. (DUNS# 00-732-1904)
 Contact Info: ti.com/support
 Form/Declaration Type: Distribute - RoHS and IEC 62474 DB
 Created on: 05/17/2022

Details for "SN65LVDS117DGG"

Current Product Information

TI part number	Lead finish/Ball material	MSL rating/peak reflow	Assembly site	Package Pins	Package body size (mm)	Total device mass (mg)*
SN65LVDS117DGG	NIPDAU	Level-2-260C-1 YEAR	TI MALAYSIA A/T	DGG 64	6.1x17.0x1.15	270.3

*Total Device Mass
 The summary mass is a rounded value and will be within approximately +/- 10% of the detailed mass value.

Environmental Ratings Information

RoHS	REACH	Green	IEC 62474 DB
Yes	Yes	Yes	Yes

Component Information

Component	Substance	CAS Number	Amount (mg)	Homogeneous Material Level		Component Level	
				Percentage %	ppm	Percentage %	ppm
Bond Wire							
Copper and Its Alloys	Iron	7439-89-6	0.000001	0.000139	1	0	0
Other Nonferrous Metals and Alloys	Beryllium	7440-41-7	0.000001	0.000139	1	0	0
Other Nonferrous Metals and Alloys	Calcium	7440-70-2	0.000002	0.000277	3	0.000001	0
Other Nonferrous Metals and Alloys	Yttrium	7440-65-5	0.000005	0.000694	7	0.000002	0
Precious Metals	Gold	7440-57-5	0.720923	99.997642	999976	0.266726	2667
Precious Metals	Silver	7440-22-4	0.000008	0.00111	11	0.000003	0
Sub-Total			0.72094	100	1000000	0.266732	2667
Die Attach Adhesive							
Precious Metals	Silver	7440-22-4	1.48532	80	800000	0.549537	5495
Thermoplastics	Epoxy	85954-11-6	0.37133	20	200000	0.137384	1374
Sub-Total			1.85665	100	1000000	0.686921	6869
Lead Frame							
Copper and Its Alloys	Copper	7440-50-8	61.450239	97.425001	974250	22.735269	227353
Copper and Its Alloys	Iron	7439-89-6	1.513786	2.4	24000	0.560068	5601
Copper and Its Alloys	Phosphorus	7723-14-0	0.009461	0.015	150	0.0035	35
Copper and Its Alloys	Tin	7440-31-5	0.018922	0.029999	300	0.007001	70
Copper and Its Alloys	Zinc	7440-66-6	0.063074	0.099999	1000	0.023336	233
Other Nonferrous Metals and Alloys	Lead	7439-92-1	0.018922	0.029999	300	0.007001	70
Sub-Total			63.074404	100	1000000	23.336176	233362
Lead Frame Plating							
Nickel and Its Alloys	Nickel	7440-02-0	0.92304	90	900000	0.341505	3415
Precious Metals	Gold	7440-57-5	0.02564	2.5	25000	0.009486	95
Precious Metals	Palladium	7440-05-3	0.07692	7.5	75000	0.028459	285
Sub-Total			1.0256	100	1000000	0.37945	3794
Mold Compound							
Other Inorganic Materials	Fused Silica	60676-86-0	169.883225	86	860000	62.853147	628531
Other Plastics and Rubber	Carbon Black	1333-86-4	0.592616	0.3	3000	0.219255	2193
Thermoplastics	Epoxy	85954-11-6	27.062793	13.7	137000	10.012652	100127
Sub-Total			197.538634	100	1000000	73.085054	730851
Semiconductor Device							
Ceramics / Glass	Doped Silicon	7440-21-3	6.069723	100	1000000	2.245667	22457
Sub-Total			6.069723	100	1000000	2.245667	22457
Total			270.285951			100	1000000

Important Note

The ppm calculations are at the homogeneous material level and are maximum concentration values. The ppm displayed represents the homogeneous material with the highest ppm for that substance. The amount (mg) calculations represent the maximum total amount of each substance within the component.
 The ppm calculations are at the component level and are average concentration values. The amount (mg) calculations represent the average total amount of each substance within the component.
[See Glossary of Terms for more details.](#)

Important Part Information

There is a remote possibility the Customer Part Number (CPN) your company uses could reference more than one TI part number. This is due to two or more users (EMSI or subcontractors) using the same CPN for different TI part numbers. If this occurs, please check your Customer Part Number and cross reference it with the TI part number seen on this page.

Product Content Methodology

[For an explanation of the methods used to determine material weights. See Product Content Methodology](#)

Material Declaration Certificate for Semiconductor IC Packaged Products

TI certifies that the material content information provided by TI is representative and accurate to the best of their knowledge based on material information provided by its suppliers and their combination into finished IC packaged products. TI semiconductor products designated to be "Pb-free", "Green" or "RoHS Exempt" fully meets the latest EU RoHS Directive requirements along with other legislation as seen in the former JIG-101 list that has been transferred to the IEC 62474 database.

Important Information/Disclaimer

TI bases its material content information on information provided by third-party suppliers and has taken, and continues to take, reasonably diligent steps to provide any required or available information. TI may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers may consider certain information to be proprietary, and thus certain information may not be available for release by TI. The material content information is provided by TI "as is."

[For additional information, please contact TI customer support.](#)

[Signature: \(click here for a fuller statement with a signed certificate\)](#)

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 For further environmental statements, please go to www.ti.com/ecoinfo
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RoHS: Means TI semiconductor products that are compliant with the current RoHS requirement that the maximum concentration values of the ten substances listed in RoHS Annex II do not exceed 0.1 % by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI semiconductor products labeled as "RoHS Compliant" are suitable for use in specified lead-free processes. TI may also reference these types of semiconductor products as "Pb-Free." These TI semiconductor products are also fully compliant with GADSL and the IEC 62474 database for electronic requirements.

RoHS Exempt: Means TI semiconductor products that contain lead (Pb) above the RoHS Annex II threshold, but that fall within one of the specific RoHS exemptions noted above or documented in <http://www.ti.com/lit/pdf/szzq088>

Green: Means the content of Chlorine (Cl) and Bromine (Br)-based flame retardants meet JS709B low halogen requirements of <=1 000ppm threshold; Antimony trioxide (Sb2O3) contained in halogen based flame retardant materials meets the <=1 000ppm threshold requirement; and Beryllium Oxide (BeO) is <=1000ppm.